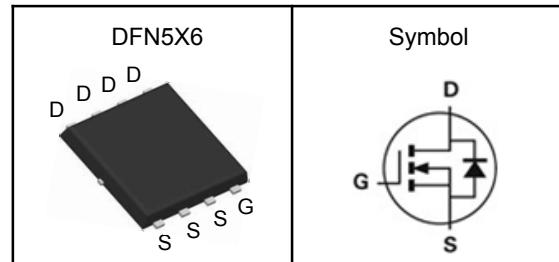


N-Channel Enhancement Mode MOSFET

Features

- Low $R_{DS(on)}$ for low conduction loss
- Reliable and Rugged
- ROHS Compliant & Halogen-Free

Pin Description



Applications

- Power Management in Desktop Computer
- DC/DC Converters

V_{DSS}	40	V
$R_{DS(ON)-Typ}$	11	$\text{m}\Omega$
I_D	25	A

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$, Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit
V_{DSS}	Drain-Source Voltage	40	V
V_{GSS}	Gate-Source Voltage	± 20	V
T_J	Maximum Junction Temperature	-55 to 150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$I_{DM}^{①}$	Pulse Drain Current Tested	100	A
I_D	Continuous Drain Current	25	A
P_D	Maximum Power Dissipation	35	W
$E_{AS}^{②}$	Avalanche Energy, Single pulse L=0.5mH	15	mJ

Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JA}^{③}$	Thermal Resistance-Junction to Ambient	50	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance-Junction to Case	3.5	$^\circ\text{C}/\text{W}$

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150°C.

Note ③ : Surface Mounted on 1in² FR-4 board with 1oz.

N-Channel Enhancement Mode MOSFET

Electrical Characteristics ($T_J=25^\circ\text{C}$, Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Static Electrical Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_D=250\mu\text{A}$	40	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$\text{V}_{\text{DS}}=40\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$	---	---	1	μA
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}$, $\text{I}_D=250\mu\text{A}$	1.1	---	2.2	V
I_{GSS}	Gate Leakage Current	$\text{V}_{\text{GS}}=\pm 20\text{V}$, $\text{V}_{\text{DS}}=0\text{V}$	---	---	± 100	nA
$\text{R}_{\text{DS(ON)}}$	Drain-Source On-state Resistance	$\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=8\text{A}$	---	11	13.8	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=4.5\text{V}$, $\text{I}_D=5\text{A}$	---	15.2	20	
Dynamic Characteristics^⑤						
C_{iss}	Input Capacitance	$\text{V}_{\text{GS}}=0\text{V}$, $\text{V}_{\text{DS}}=20\text{V}$, Freq.=1MHz	---	780	---	pF
C_{oss}	Output Capacitance		---	55	---	
C_{rss}	Reverse Transfer Capacitance		---	48	---	
$\text{T}_{\text{d(on)}}$	Turn-on Delay Time	$\text{V}_{\text{DS}}=20\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{R}_G=3\Omega$, $\text{R}_L=1\Omega$, $\text{I}_D=8\text{A}$	---	14	---	nS
T_r	Turn-on Rise Time		---	2	---	
$\text{T}_{\text{d(off)}}$	Turn-off Delay Time		---	18	---	
T_f	Turn-off Fall Time		---	4	---	
Q_g	Total Gate Charge	$\text{V}_{\text{DS}}=20\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=5\text{A}$	---	20	---	nC
Q_{gs}	Gate-Source Charge		---	1.7	---	
Q_{gd}	Gate-Drain Charge		---	2.5	---	
Source-Drain Characteristics						
$\text{V}_{\text{SD}}^{④}$	Diode Forward Voltage	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_S=8\text{A}$, $T_J=25^\circ\text{C}$	---	---	1.2	V
t_{rr}	Reverse Recovery Time	$\text{I}_F=8\text{A}$, $d\text{I}/dt=100\text{A}/\mu\text{s}$, $T_J=25^\circ\text{C}$	---	20	---	nS
Q_{rr}	Reverse Recovery Charge		---	10	---	nC

Note ④: Pulse test (pulse width 300us, duty cycle 2%).

Note ⑤ : Guaranteed by design, not subject to production testing.

N-Channel Enhancement Mode MOSFET

Typical Characteristics

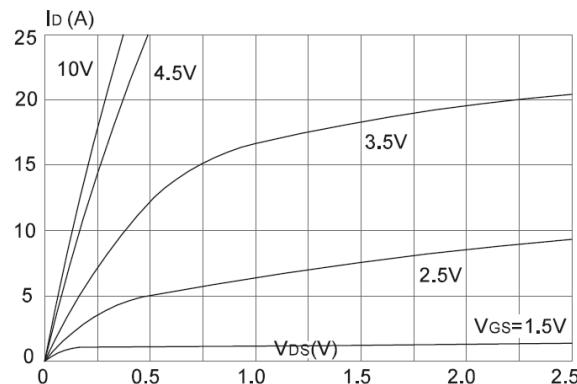


Fig.1 Output Characteristics

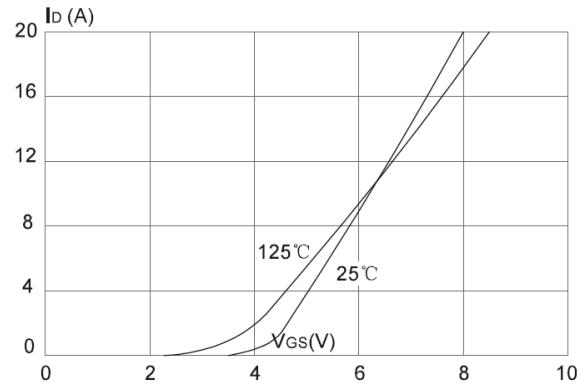


Fig.2 Typical Transfer Characteristics

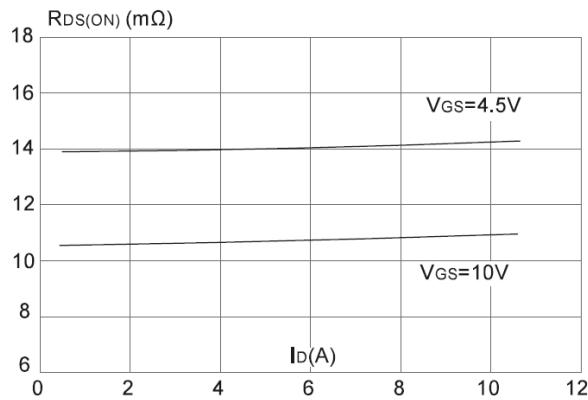


Fig.3 On-resistance VS Drain Current

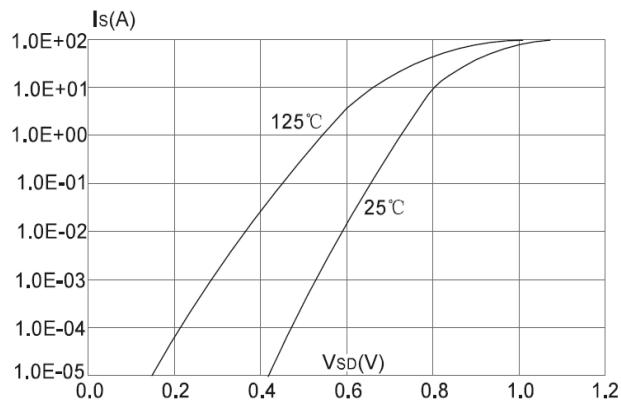


Fig.4 Body Diode Characteristics

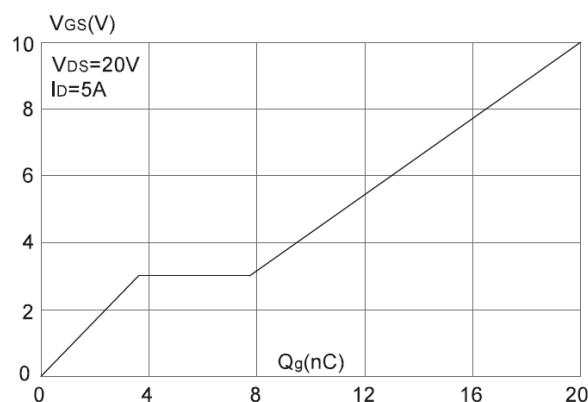


Fig.5 Gate Charge Characteristics

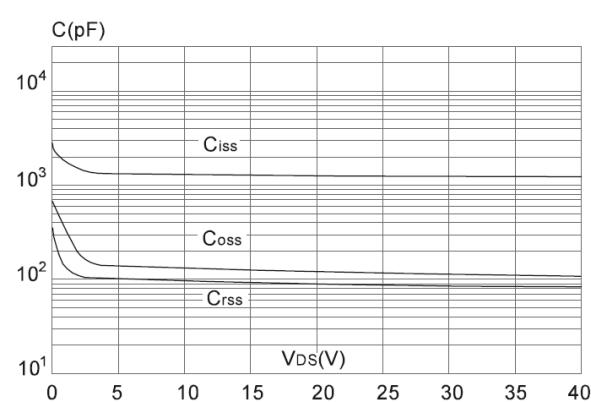


Fig.6 Capacitance Characteristics

N-Channel Enhancement Mode MOSFET

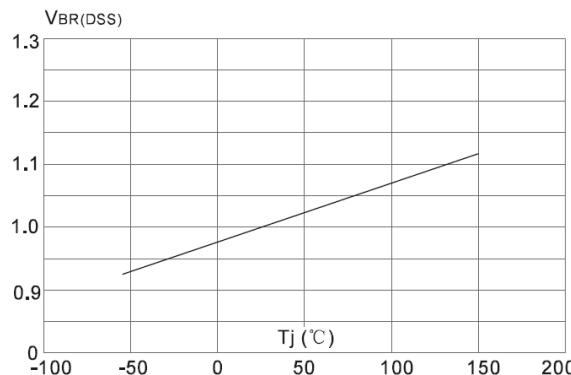


Fig.7 Normalized Breakdown Voltage VS Junction Temperature

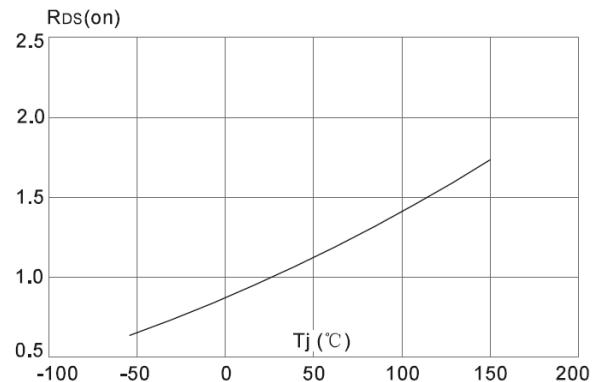


Fig.8 Normalized On-Resistance Variation VS Junction Temperature

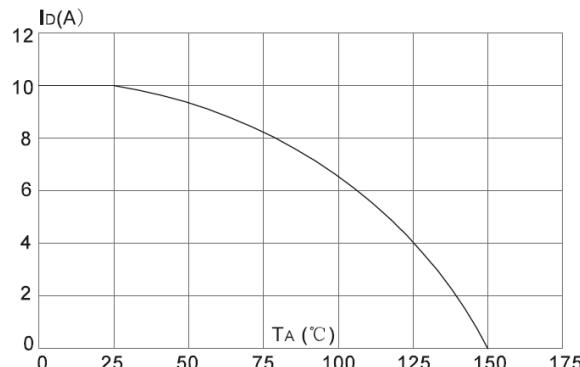


Fig.9 Maximum Continuous Drain Current VS. Ambient Temperature

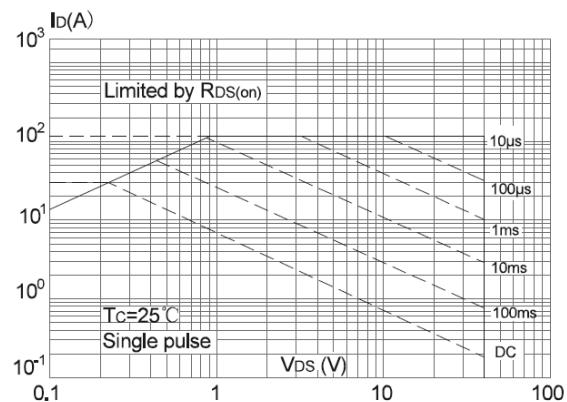


Fig.10 Safe Operating Area

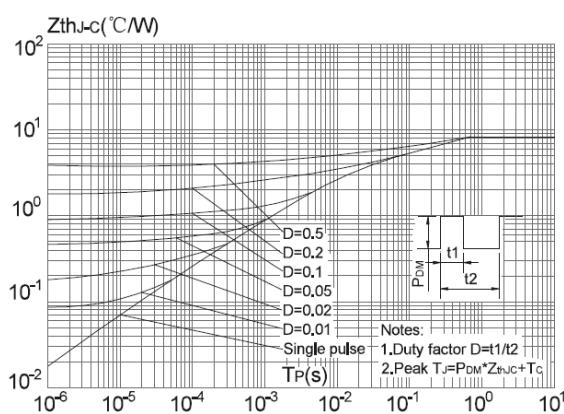
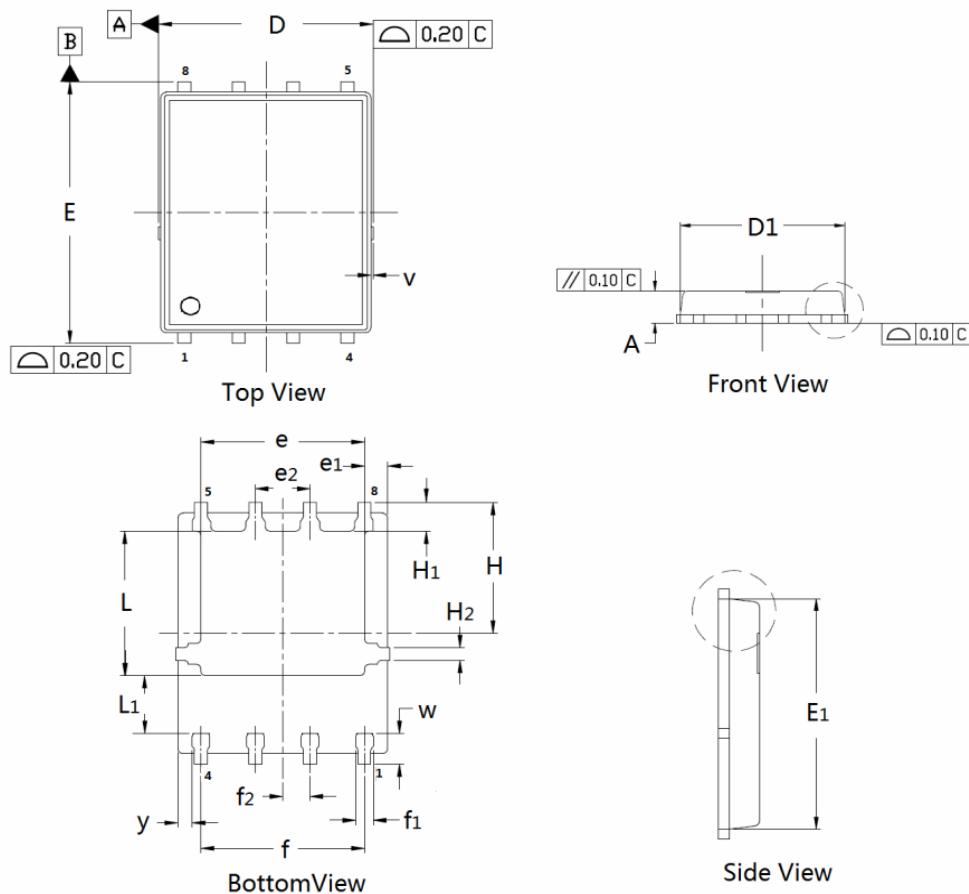


Fig.11 Transient Thermal Response Curve

N-Channel Enhancement Mode MOSFET
DFN5×6 Package Outline Data

DIMENSIONS (unit : mm)

Symbol		Typ	Max	Symbol	Min	Typ	Max
A	0.90	1.02	1.10	D	4.90	4.98	5.10
D₁	4.80	4.89	5.10	E	5.90	6.11	6.25
E₁	5.65	5.74	5.95	e	3.72	3.80	3.92
e₁	--	0.5	--	e₂	--	1.	--
f	--	3.8	--	f₁	0.31	0.37	0.51
f₂	--	0.6	--	H	--	3.	--
H₁	0.59	0.63	0.79	H₂	0.26	0.28	0.32
L	3.35	3.45	3.65	L₁	--	1.	--
V	--	0.1	--	w	0.64	0.68	0.84
y	--	0.3	--		--		--